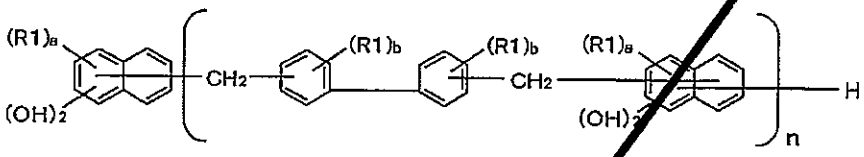
CLAIMS

1. A resin composition for encapsulating a semiconductor comprising a phenol resin (A) containing a component represented by the following general formula (1);

an epoxy resin (B); and

an inorganic filler (C),

[Chemical Formula 1]

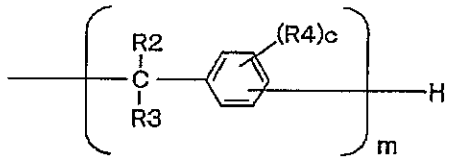


(1)

wherein, in the general formula (1), two hydroxyl groups bonded to the same naphthalene group are bonded to different carbon atoms on a naphthalene ring; R1 is each independently a hydrocarbon group having 1 to 60 carbon atoms; as are each independently an integer of 0 to 5; b is each independently an integer of 0 to 4; and n is an integer of 1 to 10.

2. The resin composition for encapsulating a semiconductor according to claim 1, wherein said phenol resin (A) contains a component in which R1 in said general formula (1) is a group represented by the following general formula (2)

[Chemical Formula 2]



(2)

wherein, in the general formula (2), R2 and R3 are each independently a hydrogen atom or a hydrocarbon group having 1 to 3 carbon atoms; R4 is each independently a hydrocarbon group having 1 to 3 carbon atoms; c is each independently an integer of 0 to 4; and m is an integer of 1 to 5.

3. The resin composition for encapsulating a semiconductor according to claim 1 or 2, wherein said phenol resin (A) contains a component with n=0 to 2 in an amount of equal to or more than 50% by mass and equal to or less than 100% by mass, based on the total phenol resin (A).

4. The resin composition for encapsulating a semiconductor according to any one of claims 1 to 3, wherein said phenol resin (A) contains a component with n=0 in an amount of equal to or more than 25% by mass and equal to or less than 70% by mass, based on the total phenol resin (A).

5. The resin composition for encapsulating a semiconductor according to any one of claims 2 to 4, wherein said phenol resin (A) contains a component in which R1 is a group represented by said general formula (2) in an amount of equal to or more than 20% by area and equal to or less than

80% by area, based on the total phenol resin (A), in the area conversion method of the gel permeation chromatography (GPC) measurement method.

6. A semiconductor device obtained by encapsulating a semiconductor element using the resin composition for encapsulating a semiconductor according to any one of claims 1 to 5.

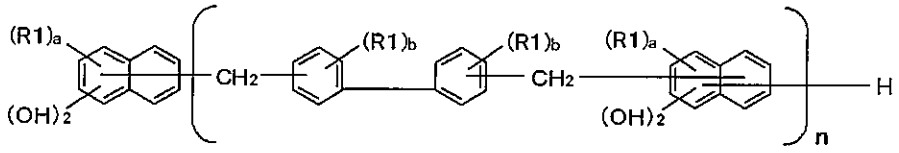
CLAIMS

1. A resin composition for encapsulating a semiconductor comprising a phenol resin (A) containing a component represented by the following general formula (1);

an epoxy resin (B); and

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[Chemical Formula 1]

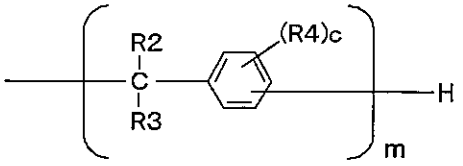


(1)

wherein, in the general formula (1), two hydroxyl groups bonded to the same naphthalene group are bonded to different carbon atoms on a naphthalene ring; R1 is each independently a hydrocarbon group having 1 to 60 carbon atoms; as are each independently an integer of 0 to 5; b is each independently an integer of 0 to 4; and n is an integer of 1 to 10.

2. The resin composition for encapsulating a semiconductor according to claim 1, wherein said phenol resin (A) contains a component in which R1 in said general formula (1) is a group represented by the following general formula (2),

[Chemical Formula 2]



(2)

wherein, in the general formula (2), R2 and R3 are each independently a hydrogen atom or a hydrocarbon group having 1

to 3 carbon atoms; R4 is each independently a hydrocarbon group having 1 to 3 carbon atoms; c is each independently an integer of 0 to 4; and m is an integer of 1 to 5.

3. The resin composition for encapsulating a semiconductor according to claim 1, wherein said phenol resin (A) contains a component with n=0 to 2 in an amount of equal to or more than 50% by mass and equal to or less than 100% by mass, based on the total phenol resin (A).

4. The resin composition for encapsulating a semiconductor according to claim 1, wherein said phenol resin (A) contains a component with n=0 in an amount of equal to or more than 25% by mass and equal to or less than 70% by mass, based on the total phenol resin (A).

5. The resin composition for encapsulating a semiconductor according to claim 2, wherein said phenol resin (A) contains a component in which R1 is a group represented by said general formula (2) in an amount of equal to or more than 20% by area and equal to or less than 80% by area, based on the total phenol resin (A), in the area conversion method of the gel permeation chromatography (GPC) measurement method.

6. A semiconductor device obtained by encapsulating a semiconductor element using the resin composition for encapsulating a semiconductor according to claim 1.